

MOC8021M, MOC8050M Photodarlington Optocoupler (No Base Connection)

Features

- High BV_{CEO}
 - Minimum 50V (MOC8021M)
 - Minimum 80V (MOC8050M)
- High current transfer ratio:
 - Minimum 1,000% (MOC8021M)
 - Minimum 500% (MOC8050M)
- 500%
- No base connection for improved noise immunity
- Underwriters Laboratory (UL) recognized
File #E90700, Volume 2
- IEC 60747-5-2 approved (ordering option V)

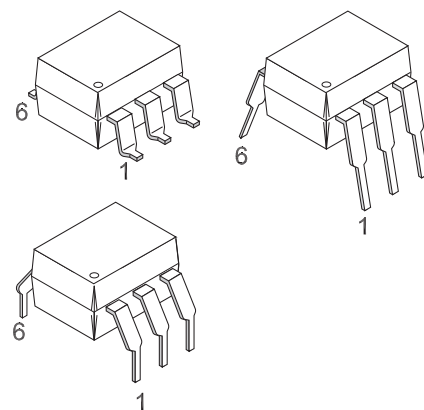
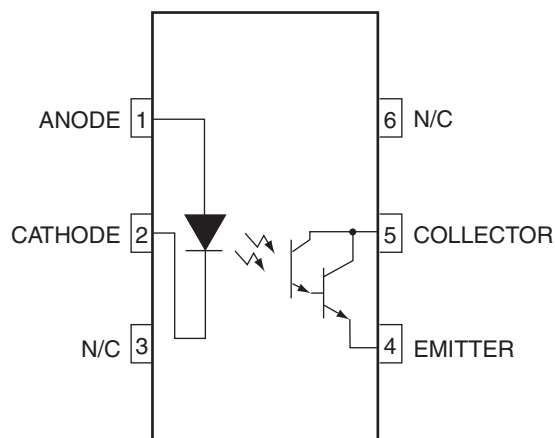
Applications

- Appliances, measuring instruments
- I/O interface for computers
- Programmable controllers
- Portable electronics
- Interfacing and coupling systems of different potentials and impedance
- Solid state relays

Description

The MOC8021M and MOC8050M are photodarlington-type optically coupled optocoupler. The devices have a gallium arsenide infrared emitting diode coupled with a silicon darlington phototransistor.

Schematic



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Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ Unless otherwise specified.)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol | Parameter | Value | Units |
|---------------------|---|----------------|----------------------------|
| TOTAL DEVICE | | | |
| T_{STG} | Storage Temperature | -55 to +150 | $^\circ\text{C}$ |
| T_{OPR} | Operating Temperature | -40 to +100 | $^\circ\text{C}$ |
| T_{SOL} | Lead Solder Temperature (Wave solder) | 260 for 10 sec | $^\circ\text{C}$ |
| P_D | Total Device Power Dissipation @ $T_A = 25^\circ\text{C}$ | 250 | mW |
| | Derate above 25°C | 2.94 | $\text{mW}/^\circ\text{C}$ |
| EMITTER | | | |
| I_F | DC/Average Forward Input Current | 60 | mA |
| V_R | Reverse Input Voltage | 3 | V |
| P_D | LED Power Dissipation @ $T_A = 25^\circ\text{C}$ | 120 | mW |
| | Derate above 25°C | 1.41 | $\text{mW}/^\circ\text{C}$ |
| DETECTOR | | | |
| V_{CEO} | Collector-Emitter Voltage | | V |
| | MOC8021M | 50 | |
| | MOC8050M | 80 | |
| P_D | Detector Power Dissipation @ $T_A = 25^\circ\text{C}$ | 150 | mW |
| | Derate above 25°C | 1.76 | $\text{mW}/^\circ\text{C}$ |
| I_C | Continuous Collector Current | 150 | mA |

Electrical Characteristics ($T_A = 25^\circ\text{C}$ Unless otherwise specified.)**Individual Component Characteristics**

| Symbol | Parameter | Test Conditions | Min. | Typ.* | Max. | Unit |
|-----------------|-------------------------------------|---------------------------------------|------|-------|------|---------------|
| EMITTER | | | | | | |
| V_F | Input Forward Voltage | $I_F = 10\text{mA}$ | | 1.18 | 2.00 | V |
| I_R | Reverse Leakage Current | $V_R = 3.0\text{V}$ | | 0.001 | 10 | μA |
| DETECTOR | | | | | | |
| BV_{CEO} | Collector-Emitter Breakdown Voltage | $I_C = 1.0\text{mA}, I_F = 0$ | | | | V |
| | MOC8021M | | 50 | 100 | | |
| | MOC8050M | | 80 | 100 | | |
| BV_{ECO} | Emitter-Collector Breakdown Voltage | $I_E = 100\mu\text{A}, I_F = 0$ | 5 | 10 | | V |
| I_{CEO} | Collector-Emitter Dark Current | $V_{CE} = 60\text{V}, I_F = 0$ | | | 1 | μA |
| C_{CE} | Capacitance | $V_{CE} = 0\text{V}, f = 1\text{MHz}$ | | 8 | | pF |

Transfer Characteristics

| Symbol | Parameter | Test Conditions | Min. | Typ.* | Max. | Unit |
|---------------------------|---|---|-------|-------|------|---------------|
| DC CHARACTERISTICS | | | | | | |
| CTR | Current Transfer Ratio, Collector to Emitter | | | | | % |
| | MOC8021M | $I_F = 10\text{mA}, V_{CE} = 5\text{V}$ | 1,000 | | | |
| | MOC8050M | $I_F = 10\text{mA}, V_{CE} = 1.5\text{V}$ | 500 | | | |
| AC CHARACTERISTICS | | | | | | |
| t_{on} | Non-Saturated Turn-on Time | $I_F = 5\text{mA}, V_{CC} = 10\text{V},$ $R_L = 100\Omega$ | | 8.5 | | μs |
| t_{off} | Turn-off Time | $I_F = 5\text{mA}, V_{CC} = 10\text{V},$ $R_L = 100\Omega$ | | 95 | | μs |

Isolation Characteristics

| Symbol | Characteristic | Test Conditions | Min. | Typ. | Max. | Units |
|-----------|--------------------------------|--|-----------|------|------|----------|
| V_{ISO} | Input-Output Isolation Voltage | $f = 60\text{Hz}, t = 1 \text{ sec.}$ | 7500 | | | Vac(pk) |
| R_{ISO} | Isolation Resistance | $V_{I-O} = 500\text{VDC}$ | 10^{11} | | | Ω |
| C_{ISO} | Isolation Capacitance | $V_{I-O} = \emptyset, f = 1\text{MHz}$ | | 0.2 | 2 | pF |

Note:*Typical values at $T_A = 25^\circ\text{C}$

Typical Performance Curves

Fig. 1 LED Forward Voltage vs. Forward Current

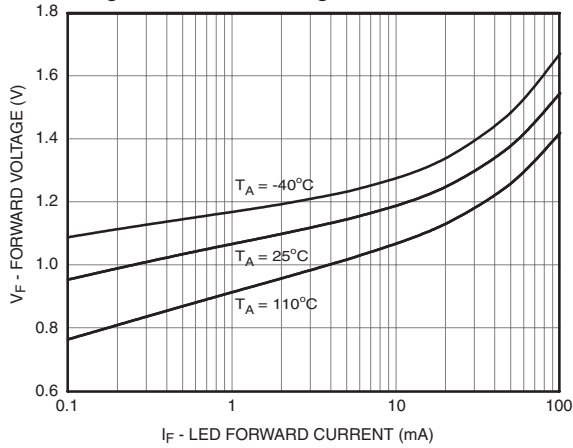


Fig. 2 Normalized CTR vs. Forward Current

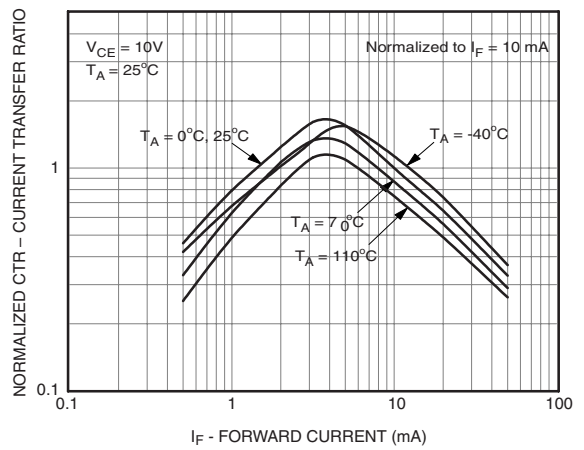


Fig. 3 Normalized CTR vs. Ambient Temperature

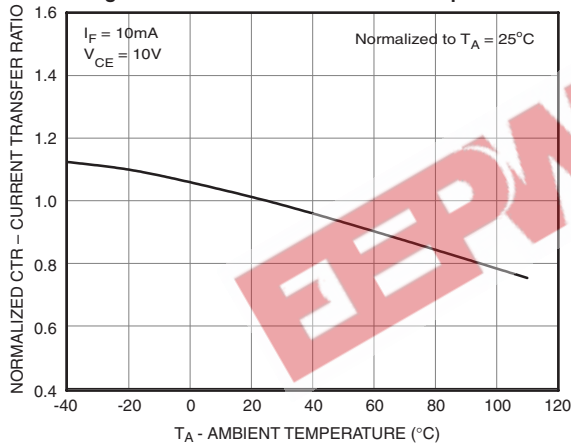


Fig. 4 Turn-on Time vs. Forward Current

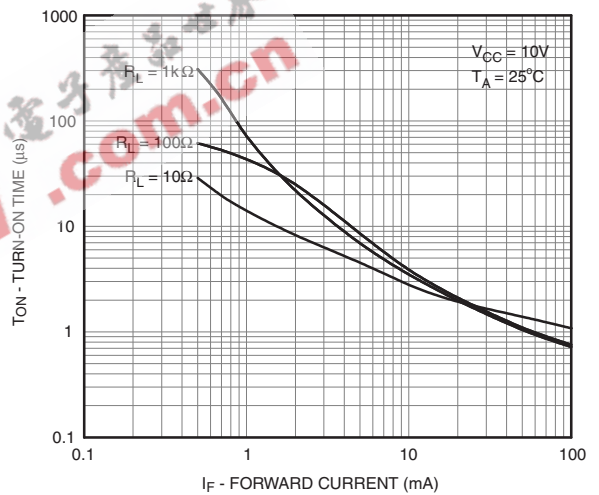


Fig. 5 Turn-off Time vs. Forward Current

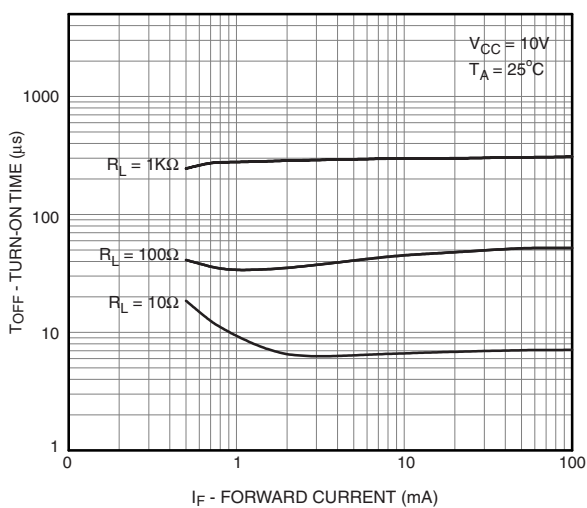
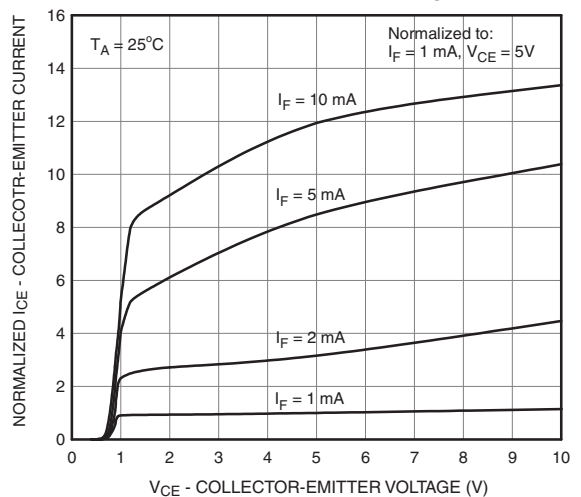
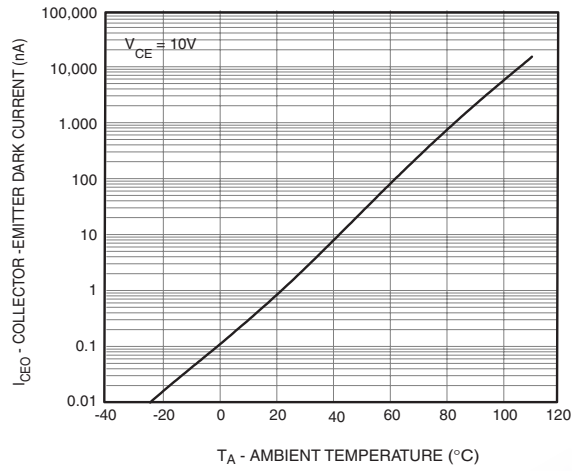


Fig. 6 Normalized Collector-Emitter Current vs. Collector-Emitter Voltage

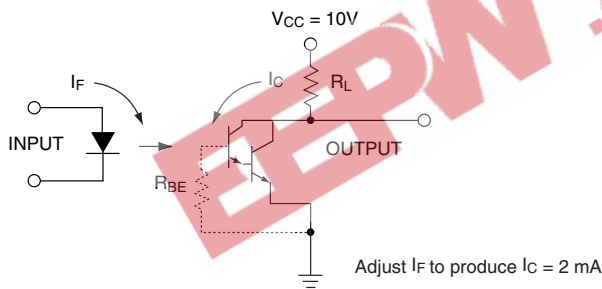


Typical Performance Curves (Continued)

Fig. 7 Dark Current vs. Ambient Temperature



TEST CIRCUIT



WAVE FORMS

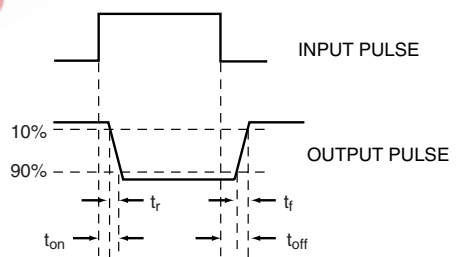
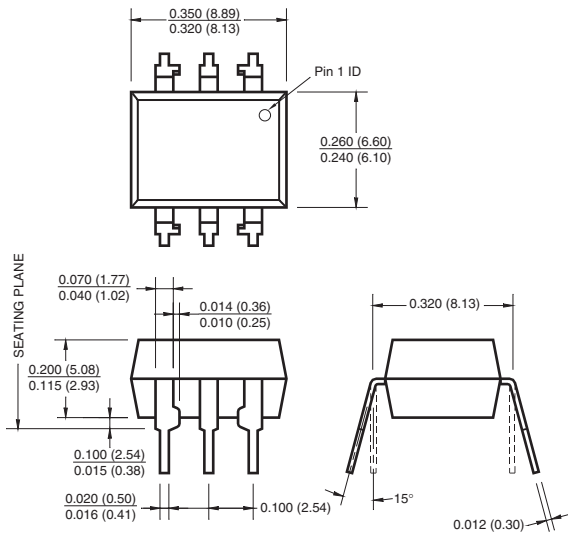


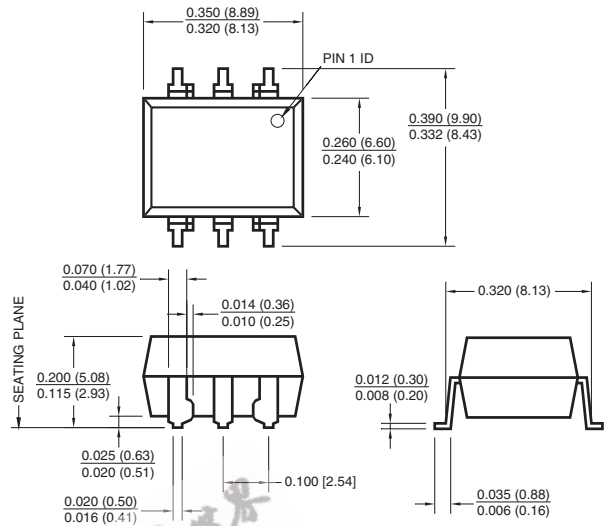
Figure 8. Switching Time Test Circuit and Waveforms

Package Dimensions

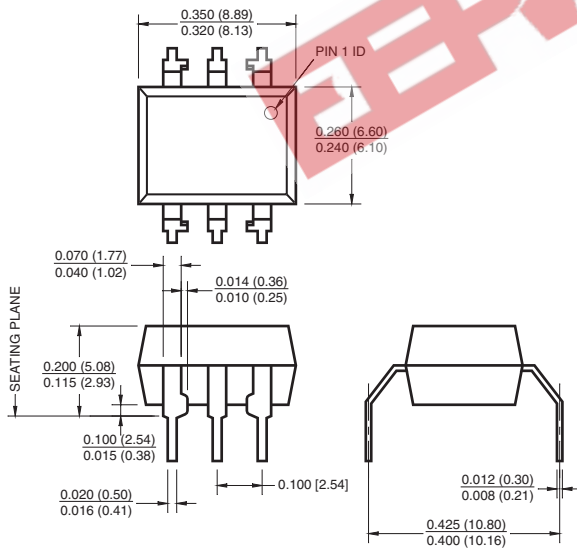
Through Hole



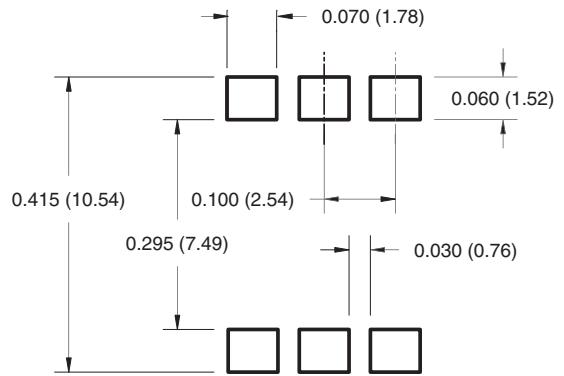
Surface Mount



0.4" Lead Spacing



Recommended Pad Layout for Surface Mount Leadform



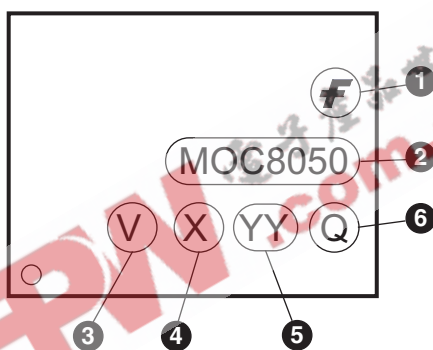
Note:

All dimensions are in inches (millimeters).

Ordering Information

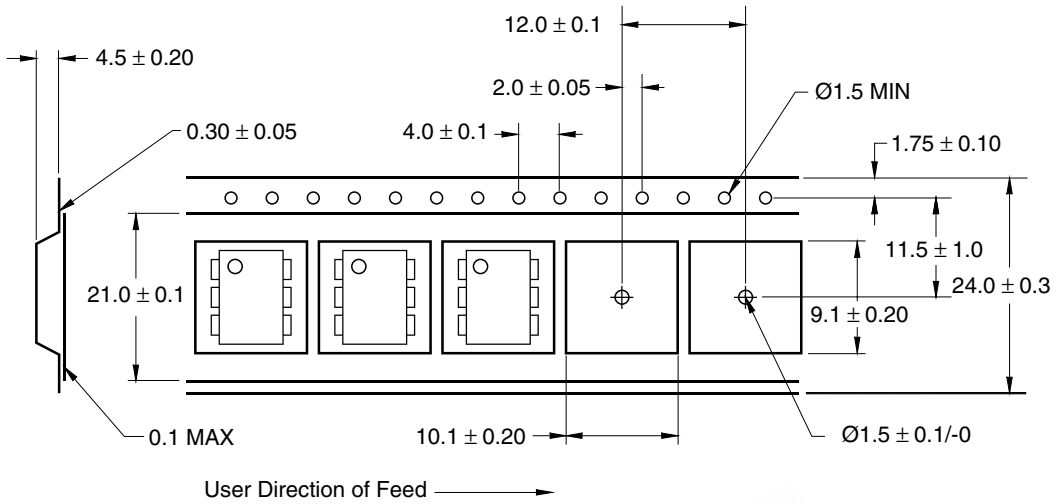
| Option | Order Entry Identifier (Example) | Description |
|-----------|----------------------------------|--|
| No suffix | MOC8050M | Standard Through Hole Device (50 parts per tube) |
| S | MOC8050SM | Surface Mount Lead Bend |
| SR2 | MOC8050SR2M | Surface Mount; Tape and Reel |
| T | MOC8050TM | 0.4" Lead Spacing |
| V | MOC8050VM | IEC60747-5-2 |
| TV | MOC8050TVM | IEC60747-5-2, 0.4" Lead Spacing |
| SV | MOC8050SVM | IEC60747-5-2, Surface Mount |
| SR2V | MOC8050SR2VM | IEC60747-5-2, Surface Mount, Tape and Reel |

Marking Information



| Definitions | |
|-------------|--|
| 1 | Fairchild logo |
| 2 | Device number |
| 3 | VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table) |
| 4 | One digit year code, e.g., '7' |
| 5 | Two digit work week ranging from '01' to '53' |
| 6 | Assembly package code |

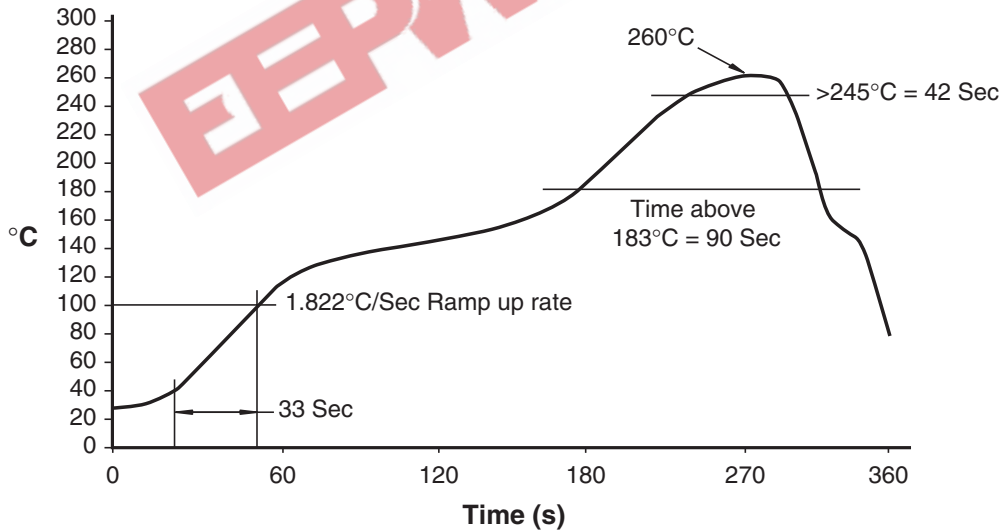
Tape Dimensions



Note:

All dimensions are in millimeters.

Reflow Soldering Profile





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|--------------------------|------------------------|--|
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